

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jeong Seok Lee</td> <td>01/07/2013</td> </tr> <tr> <td>In Tae Kim</td> <td>01/07/2013</td> </tr> <tr> <td>Jae Sik Park</td> <td>01/07/2013</td> </tr> <tr> <td>Dai Hyun Jung</td> <td>01/07/2013</td> </tr> </tbody> </table>		Name	Execution Date	Jeong Seok Lee	01/07/2013	In Tae Kim	01/07/2013	Jae Sik Park	01/07/2013	Dai Hyun Jung	01/07/2013
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In Tae Kim	01/07/2013										
Jae Sik Park	01/07/2013										
Dai Hyun Jung	01/07/2013										
RECEIVING PARTY DATA											
Name:	Amkor Technology, Inc.										
Street Address:	1900 South Price Road										
City:	Chandler										
State/Country:	ARIZONA										
Postal Code:	85286-6604										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13739547</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13739547						
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Application Number:	13739547										
CORRESPONDENCE DATA											
Fax Number:	8316550888										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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Correspondent Name:	McKay and Hodgson, LLP										
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NAME OF SUBMITTER:	Serge J. Hodgson										
Total Attachments: 3 source=GK0054_as_filed_assign#page1.tif source=GK0054_as_filed_assign#page2.tif source=GK0054_as_filed_assign#page3.tif											

CH \$40.00 13739547

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, I,

Jeong Seok Lee	of	301-1704, Sinchang 3 Cha Hoban Apt., Sinchang-dong, Gwangsan-gu Gwangju, Korea
In Tae Kim	of	102-1006, Samho Apt., Ilgok-dong, Buk-gu Gwangju, Korea
Jae Sik Park	of	106-703, Kumho Apt., Munheung 1-dong, Buk-gu Gwangju, Korea
Dai Hyun Jung	of	106-404, Moaelgaa Apt., Suwan-dong, Gwangsan-gu, Gwangju, Korea

hereby sell, assign and transfer to Amkor Technology, Inc., a Delaware corporation, having a place of business at 1900 South Price Road, Chandler, AZ 85286-6604, its successors and assigns, the entire right, title and interest throughout the world in my invention in

SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE SAME

for which I have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; I authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and I request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 7 day of Jan, 2013.

01 26 13  
Jeong Seok Lee  
(Full Name)

Witnessed by: [Signature]  
Signature

Jan 7, 2013  
Date

Dai Hyun Na  
Printed Name

Assignment (continued)

Executed this 7 day of Jan, 2013.

IT Kim  
In Tae Kim  
(Full Name)

Witnessed by:

[Signature]  
Signature

Jan 7, 2013  
Date

Do Hyun Na  
Printed Name

Executed this 7 day of Jan, 2013.

J. Park  
Jae Sik Park  
(Full Name)

Witnessed by:

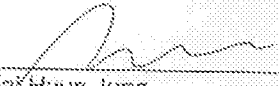
[Signature]  
Signature


Jan 7, 2013  
Date

Do Hyun Na  
Printed Name

Assignment (continued)

Executed this 7 day of Jan, 2013.

  
\_\_\_\_\_  
Dai Hyun Jung  
(Full Name)

Witnessed by:   
\_\_\_\_\_  
Signature

Jan 7, 2013  
\_\_\_\_\_  
Date

Dai Hyun Na  
\_\_\_\_\_  
Printed Name